

HDAF SERIES

(2.00 mm) .0787"

RUGGED ELEVATED HIGH-DENSITY ARRAY

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

3.4 A per pin

(6 adjacent pins powered)

Operating Temp Range:

-55 °C to +125 °C

Working Voltage:

200 VAC

Mated Cycles:

100

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

Mates with:
HDAM

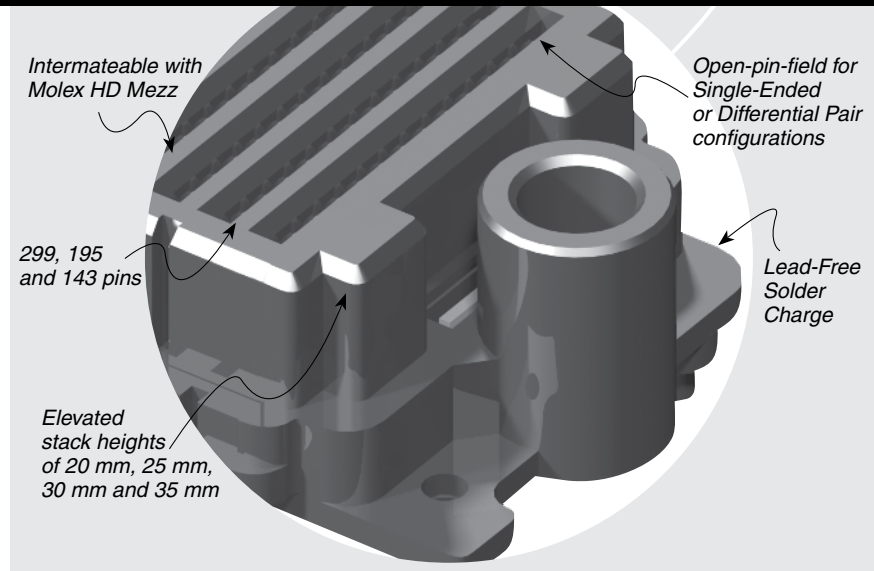
Intermateable with
Molex HD Mezz

Open-pin-field for
Single-Ended
or Differential Pair
configurations

299, 195
and 143 pins

Lead-Free
Solder
Charge

Elevated
stack heights
of 20 mm, 25 mm,
30 mm and 35 mm



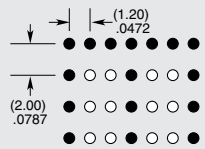
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



HDAF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	13	SOLDER TYPE	OPTION	PACKAGING
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tails and guide pins		-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge	-P = Pick & Place Pad	Leave blank for tray packaging -TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

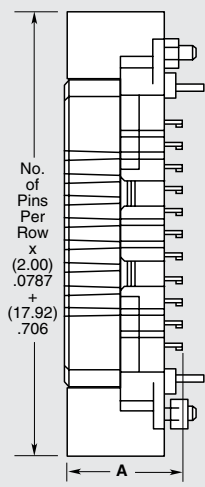
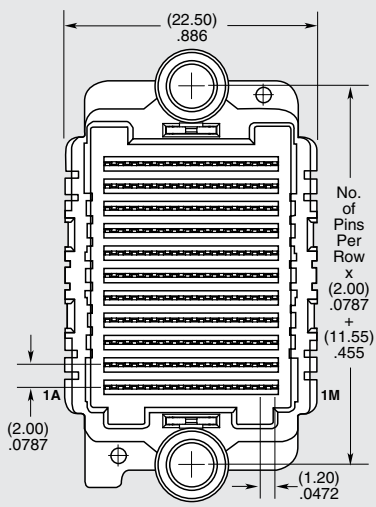
*2:1 S:G Ratio

ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
- Other platings

Notes:
HD Mezz is a trademark of Molex Incorporated

Some lengths, styles and options are non-standard, non-returnable.



LEAD STYLE	A
-08.0	(10.51) .414
-18.0	(20.51) .807